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AEHR TEST SYSTEMS ANNOUNCES FOX-15™ FULL WAFER CONTACT TEST AND BURN-IN SYSTEM

Fremont, CA (October 23, 2007) - Aehr Test Systems (Nasdaq: AEHR), a leading supplier of semiconductor test and burn-in equipment, today announced the availability of the FOX-15 full wafer contact test and burn-in system. The FOX-15 is the fourth and latest member of the FOX family of full wafer contact systems and is focused on parallel testing and burning-in up to 15 wafers at a time. As with all members of the FOX product family, the FOX-15 contacts every die on each wafer simultaneously.

“The FOX-15 system is designed for use with wafers that require test and burn-in times typically measured in hours,” said Steve Steps, senior director of wafer level burn-in and test at Aehr Test Systems. “For ultra-high reliability applications, such as automotive, we believe that the FOX-15 system is a cost-effective solution for producing tested and burned-in die or Known Good Die (KGD) for use in multi-chip packages. Using burned-in die in multi-chip packages helps assure the reliability of the final product and lowers costs by increasing the yield of high-cost multi-chip packages.”

“The FOX-15 full wafer test and burn-in system represents a natural progression for our leadership position in full wafer contact burn-in and massively parallel test,” said Rhea Posedel, chairman and chief executive officer of Aehr Test. “The FOX-15 system widens our addressable market to include numerous high volume devices such as DRAMS, which have long test and burn-in times. Another member of the FOX product family, the FOX-1, is focused on wafers requiring shorter test and/or burn-in times, typically measured in minutes. We are excited about the sales potential for the entire FOX family as it moves the company into a rapidly expanding market for massively parallel testing and burn-in at the wafer level.”

FOX-15 Features Include:

- 15 Wafer Slots
- Wafer sizes from 2 inches (50.8mm) up to 300mm
- Parallel test and burn-in of 1000s of die per wafer
- Individual die power channels to isolate shorted die
- General purpose memory and logic pattern generator
- Independent test electronics per wafer

- Liquid temperature control maintains chuck temperature $\pm 3^{\circ}\text{C}$
- Up to 1000W power dissipation per wafer

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a leading worldwide provider of systems for burning-in and testing memory and logic integrated circuits and has an installed base of more than 2,500 systems worldwide. Aehr Test has developed and introduced several innovative products, including the FOX, MTX and MAX systems and the DiePak[®] carrier. The FOX system is a full wafer contact test and burn-in system. The MTX system is a massively parallel test system designed to reduce the cost of memory testing by performing both test and burn-in on thousands of devices simultaneously. The MAX system can effectively burn-in and functionally test complex devices, such as digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company's website at www.aehr.com.

Safe Harbor Statement

This release contains forward-looking statements that involve risks and uncertainties relating to projections regarding customer demand and acceptance of Aehr Test's products. Actual results may vary from projected results. These risks and uncertainties include, without limitation, acceptance by customers of the FOX technology, acceptance by customers of the FOX systems and contactors shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission (SEC) for a more detailed description of the risks facing our business. The Company disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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